# **ULSI** Technology

### EDITED BY

# C. Y. Chang

Chair Professor, College of Electrical Engineering and Computer Science National Chiao Tung University Director, National Nano Device Laboratories Hsinchu, Taiwan, ROC

### S. M. Sze

UMC Chair Professor

Department of Electronics Engineering

Director, Microelectronics and Information Systems Research Center

National Chiao Tung University

Hsinchu, Taiwan, ROC

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